**Product data sheet** 

# 1. General description

WMS20N500SK is a high performance super logic level N-channel MOSFET in SOT23 package, which utilizes advanced Trench MOSFET technology to provide low  $R_{\rm DS(on)}$  and gate charge. It is designed and qualified in a wide range of industrial and consumer applications.



## 2. Features and benefits

- Advance High Cell Density Trench Technology
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Capacitance to Minimize Switching Losses
- Optimized Gate Charge to Minimize Driver Losses
- RoHS Compliant, Halogen Free and Lead Free

# 3. Applications

- Load Switch
- General PWM Applications

## 4. Quick reference data

### Table 1. Quick reference data

Parameter	Conditions	Notes		Values		Unit
maximum rating						
drain-source voltage				20		V
gate-source voltage				±10		V
continuous drain current	V <sub>GS</sub> = 4.5 V; T <sub>a</sub> = 25 °C			4.2		Α
power dissipation	T <sub>a</sub> = 25 °C		1.4			W
junction temperature			-55 to 150		°C	
Parameter	Conditions	Notes	Min Typ Max		Max	Unit
aracteristics						
drain-source on-state	$V_{GS} = 4.5 \text{ V}, I_D = 4.2 \text{ A}$		-	34	50	mΩ
resistance	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 3 A		-	45	65	mΩ
characteristics				•	,	
total gate charge	$I_D = 4.2 \text{ A}; V_{DS} = 10 \text{ V}; V_{GS} = 4.5 \text{ V}$		-	2.5	-	nC
	maximum rating  drain-source voltage gate-source voltage continuous drain current power dissipation junction temperature  Parameter  aracteristics drain-source on-state resistance  characteristics	maximum rating         drain-source voltage         gate-source voltage         continuous drain current $V_{GS} = 4.5 \text{ V}$ ; $T_a = 25 \text{ °C}$ power dissipation $T_a = 25 \text{ °C}$ junction temperature         Parameter       Conditions         aracteristics         drain-source on-state resistance $V_{GS} = 4.5 \text{ V}$ , $I_D = 4.2 \text{ A}$ $V_{GS} = 2.5 \text{ V}$ , $I_D = 3 \text{ A}$	maximum rating         drain-source voltage       gate-source voltage         continuous drain current $V_{GS} = 4.5 \text{ V}$ ; $T_a = 25 \text{ °C}$ power dissipation $T_a = 25 \text{ °C}$ junction temperature       Variantee         Parameter       Conditions         drain-source on-state resistance $V_{GS} = 4.5 \text{ V}$ , $I_D = 4.2 \text{ A}$ $V_{GS} = 2.5 \text{ V}$ , $V_{CS} = 3.5 \text{ V}$ characteristics	maximum rating         drain-source voltage       gate-source voltage         continuous drain current $V_{GS} = 4.5 \text{ V}$ ; $T_a = 25 \text{ °C}$ power dissipation $T_a = 25 \text{ °C}$ junction temperature       -         Parameter       Conditions         drain-source on-state resistance $V_{GS} = 4.5 \text{ V}$ , $I_D = 4.2 \text{ A}$ $V_{GS} = 2.5 \text{ V}$ , $I_D = 3 \text{ A}$ -         characteristics	maximum rating       20         gate-source voltage $\pm 10$ continuous drain current $V_{GS} = 4.5 \text{ V}$ ; $T_a = 25 \text{ °C}$ $4.2$ power dissipation $T_a = 25 \text{ °C}$ $1.4$ junction temperature $-55 \text{ to } 15$ Parameter       Conditions       Notes       Min       Typ         aracteristics         drain-source on-state resistance $V_{GS} = 4.5 \text{ V}$ , $I_D = 4.2 \text{ A}$ $ 34$ characteristics	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	2	D
2	S	source	3 □	
3	D	drain	1 2	sym300 S

# 6. Ordering information

**Table 3. Ordering information** 

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WMS20N500SK	SOT23	WMS20N500SKX	Reel	3000	SOT23L	22-Aug-2022

# 7. Marking

### Table 4. Marking codes

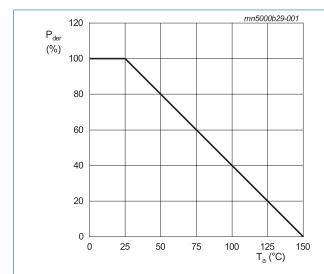
Type number	Marking codes
WMS20N500SK	AB

# 8. Limiting values

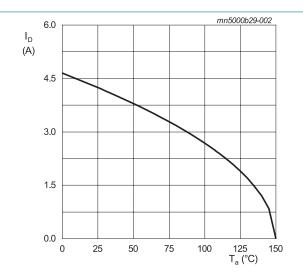
## **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V <sub>DS</sub>	drain-source voltage			20	V
V <sub>GS</sub>	gate-source voltage			±10	V
I <sub>D</sub>	continuous drain current	V <sub>GS</sub> = 4.5 V; T <sub>a</sub> = 25 °C		4.2	Α
		V <sub>GS</sub> = 4.5 V; T <sub>a</sub> = 70 °C		3.3	Α
I <sub>DM</sub>	pulsed drain current	t <sub>p</sub> = 10 μs; T <sub>a</sub> = 25 °C		16.8	Α
P <sub>tot</sub>	power dissipation	T <sub>a</sub> = 25 °C		1.4	W
T <sub>stg</sub>	storage temperature			-55 to 150	°C
T <sub>j</sub>	junction temperature			-55 to 150	°C



P<sub>der</sub> = (P<sub>tot</sub> / P<sub>tot(25 °C)</sub>) x 100% Fig. 1. Normalized total power dissipation as a function of ambient temperature



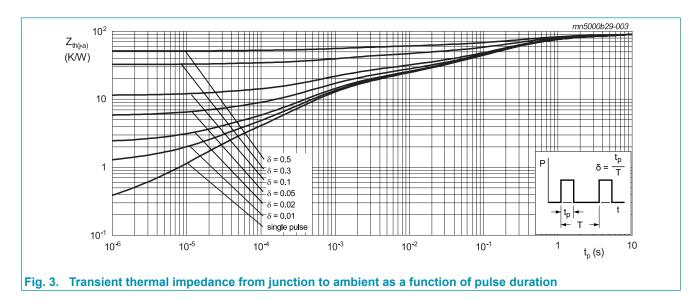
V<sub>GS</sub> = 4.5 V
Fig. 2. Continuous Drain Current as a function of ambient temperature

## 9. Thermal & Mechanical characteristics

Table 6. Thermal & Mechanical characteristics

S	ymbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R	R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	t ≤ 10s	[1]	-	72	90	K/W
			in free air	[1]	-	95	120	K/W

[1] Surface mount on FR4 board of 1 inch2, 1 oz copper.



# 10. Characteristics

## **Table 7. Characteristics**

T<sub>i</sub> = 25 °C unless otherwise noted

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics		,			'	
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V$		20	-	-	V
$V_{\text{GS(th)}}$	gate-source threshold voltage	$I_D = 250 \ \mu A; \ V_{DS} = V_{GS}$		0.45	0.7	1.1	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 0 V		-	-	1	μA
		V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 125 °C		-	-	10	μA
I <sub>GSS</sub>	gate leakage current	$V_{GS} = \pm 10 \text{ V}; V_{DS} = 0 \text{ V}$		-	-	±100	nA
R <sub>DS(on)</sub>	drain-source on-state	V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 4.2 A		-	34	50	mΩ
	resistance	$V_{GS} = 2.5 \text{ V}; I_D = 3 \text{ A}$		-	45	65	mΩ
R <sub>G</sub>	gate resistance	f = 1 MHz		-	4.2	-	Ω
Dynamic	characteristics						
Q <sub>G(tot)</sub>	total gate charge	$I_D = 4.2 \text{ A}; V_{DS} = 10 \text{ V}; V_{GS} = 4.5 \text{ V}$		-	2.5	-	nC
Q <sub>GS</sub>	gate-source charge			-	0.5	-	nC
$Q_{GD}$	gate-drain charge			-	0.6	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 10 V; V <sub>GS</sub> = 0 V; f = 1 MHz		-	178	-	pF
C <sub>oss</sub>	output capacitance			-	40	-	pF
C <sub>rss</sub>	reverse transfer capacitance			-	35	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 10 \text{ V}; V_{GS} = 4.5 \text{ V}; R_G = 6 \Omega;$		-	6.2	-	ns
t <sub>r</sub>	rise time	$I_{D} = 4.2 \text{ A}$		-	11	-	ns
$t_{\text{d(off)}}$	turn-off delay time			-	23	-	ns
t <sub>f</sub>	fall time			-	9.0	-	ns
Source-d	rain diode						
V <sub>SD</sub>	source-drain voltage	V <sub>GS</sub> = 0 V; I <sub>S</sub> = 1 A		-	0.71	1	V
		V <sub>GS</sub> = 0 V; I <sub>S</sub> = 1 A; T <sub>j</sub> = 125 °C		-	0.59	-	V
Is	body-diode continuous current	T <sub>a</sub> = 25 °C		-	-	2	А
t <sub>rr</sub>	reverse recovery time	$V_{GS} = 0 \text{ V}; I_S = 4.2 \text{ A}; di/dt = 100 \text{ A/}\mu\text{s}$		-	11	-	ns
Q <sub>rr</sub>	reverse recovered charge			-	2.6	-	nC
I <sub>rrm</sub>	reverse recovery current			-	0.4	-	Α

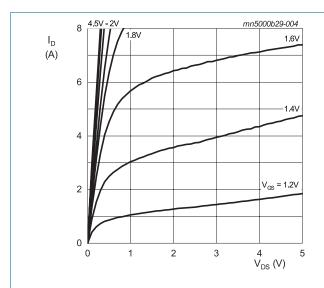


Fig. 4. Drain current as a function of drain-source voltage; typical values

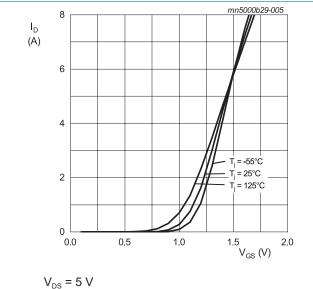
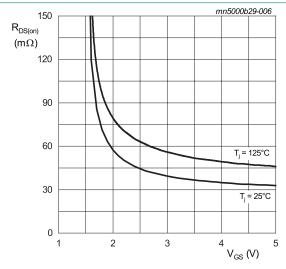


Fig. 5. Drain current as a function of gate-source voltage; typical values



V<sub>GS</sub> = 4.5 V; I<sub>D</sub> = 4.2 A

Fig. 6. Drain-source on-state resistance as a function of gate-source voltage; typical values

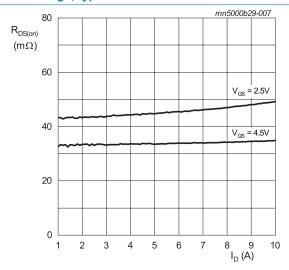
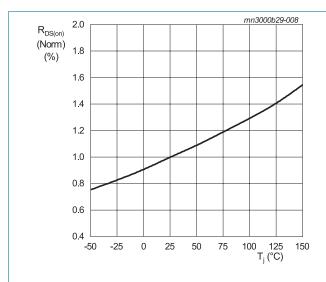
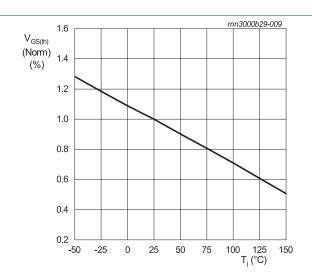


Fig. 7. Drain-source on-state resistance as a function of drain current; typical values



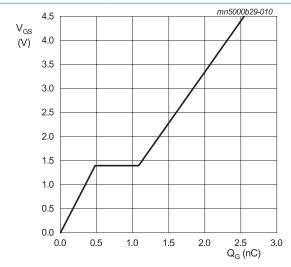
 $V_{GS} = 4.5 \text{ V}; I_{D} = 4.2 \text{ A}$ 

Fig. 8. Normalized drain-source on-state resistance as a function of junction temperature



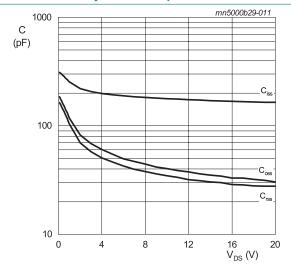
 $V_{GS}$  =  $V_{GS}$ ;  $I_D$  = 250  $\mu A$ 

Fig. 9. Normalized gate-source threshold voltage as a function of junction temperature



 $I_D$  = 4.2 A;  $V_{DS}$  = 10 V Fig. 10. Gate-source voltage as a function of gate

charge; typical values

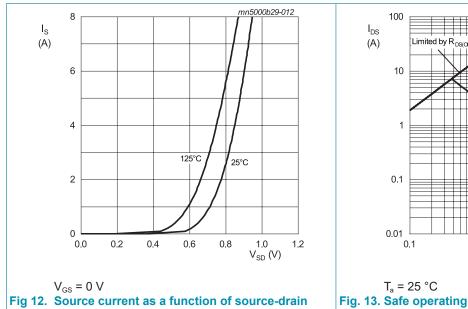


V<sub>GS</sub> = 0 V; f = 1 MHz

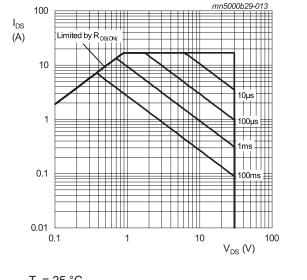
Fig 11. Capacitances as a function of drain-source voltage; typical values

voltage; typical values

**N-Channel Silicon MOSFET** 

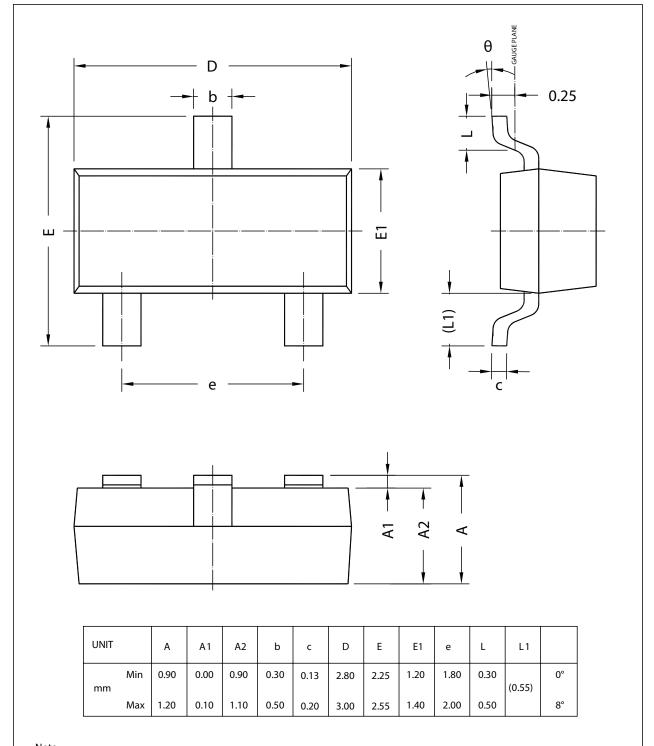






T<sub>a</sub> = 25 °C Fig. 13. Safe operating area

# 11. Package outline



Note:

1. All dimensions don't include mold flash and metal protrusion.

# 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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